EAST Search History

EAST Search History (Prior Art)

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	1	"10594844"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2010/11/04 15:29
L2	4228	257/778.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2010/11/04 15:31
L3	1605	257/779.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2010/11/04 15:31
L4	1953	257/780.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2010/11/04 15:31
L5	3504	257/e21.511.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2010/11/04 15:31
L6	551	257/e23.06.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2010/11/04 15:31
L7	9865	2 or 3 or 4 or 5 or 6	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2010/11/04 15:32
L8	270	7 and ((solder resist or solder $1resist) same (height or thick $4))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2010/11/04 15:34
L9	153	8 and @ad<="20040329"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2010/11/04 15:34

S1	5	"2004103928"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/10/28 14:14
S2	2	"20040046252"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/10/28 14:20
S3	4	"2002057186"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/10/28 17:24
S4	2	"2003179100"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/10/28 17:25
S5	3	"2002343829"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/10/28 17:25
S6	2	"2000138255"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/10/28 17:26
S7	1	"10594844"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/10/28 17:38
S8	2	"20040046252"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/10/28 17:43
S9	1	"9172035"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/10/28 17:53
S10	0	"009172035"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/10/28 17:53
S11	2	9-172035	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/10/28 17:54

S12	2	"5088189".pn.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/10/28 18:05
S13	2	"6028011".pn.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/10/28 18:05
S14	107091	wiring near board	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/10/28 18:05
S15	1787	solder near resist near film	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/10/28 18:06
S16	16	S14 near S15	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/10/28 18:06
S17	2	US "20040046252"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/11/03 10:03
S18	914276	(wiring or circuit or (printed near circuit) or support) near (board or substrate or base) or PCB	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/11/03 10:28
S19	45462	(flip near chip) or flip-chip	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/11/03 10:28
S20	56306	(solder near bump$1) or (solder near ball$1)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/11/03 10:29
S21	6292	S18 same (solder near resist)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/11/03 10:29
S22	13703	S18 and S19 and S20	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/11/03 10:29

S23	543	S19 and S20 and S21	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/11/03 10:30
S24	446	S23 and thickness	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/11/03 10:47
S25	4	"11077930"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/11/03 11:04
S26	0	("7005585").URPN.	USPAT	ADJ	ON	2008/11/03 11:05
S27	14	"4859808"	USPAT	ADJ	ON	2008/11/03 11:05
S28	1	"4859808".pn.	USPAT	ADJ	ON	2008/11/03 11:30
S29	1	"5218234".pn.	USPAT	ADJ	ON	2008/11/03 11:31
S30	1	"5378859".pn.	USPAT	ADJ	ON	2008/11/03 11:31
S31	1	"5397864".pn.	USPAT	ADJ	ON	2008/11/03 11:32
S32	1	"5650595".pn.	USPAT	ADJ	ON	2008/11/03 11:33
S33	0	S23 and (thickness ner resin)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/11/03 12:00
S34	49	S23 and (thickness near resin)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/11/03 12:00
S35	3	S23 and (thickness near underfill)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/11/03 12:06
S36	111	(thickness near underfill)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/11/03 12:07

S37	52	S23 and (thickness near solder resist)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/11/03 12:17
S38	3	"20050155790"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/11/03 13:29
S39	525	S23 and method	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/11/03 13:58
S40	125	S39 and pressing	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/11/03 13:58
S41	0	S39 and (deposit near liquid near resin)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/11/03 14:36
S42	11	(deposit near liquid near resin)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/11/03 14:36
S43	54	S39 and (liquid near resin)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/11/03 14:36
S44	914276	(wiring or circuit or (printed near circuit) or support) near (board or substrate or base) or PCB	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/11/03 18:49
S45	45462	(flip near chip) or flip-chip	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/11/03 18:49
S46	56306	(solder near bump$1) or (solder near ball$1)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/11/03 18:49
S47	6292	S44 same (solder near resist)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/11/03 18:49

S48	543	S45 and S46 and S47	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/11/03 18:49
S49	525	S48 and method	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/11/03 18:49
S50	54	S49 and (liquid near resin)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/11/03 18:49
S51	20	S50 and plasma	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/11/03 18:49
S52	117	S49 and plasma	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/11/03 18:52
S53	0	("2005/0155790").URPN.	USPAT	ADJ	ON	2008/11/03 19:42
S54	0	"2002256288"	USPAT	ADJ	ON	2008/11/03 19:42
S55	1	"2002-256288"	USPAT	ADJ	ON	2008/11/03 19:42
S61	159323	bump or ball SAME (air bubble)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/04/28 13:35
S62	1407322	aperture	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/04/28 13:36
S63	21805	S61 and S62	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/04/28 13:36
S64	3	US "20050155790"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/04/28 15:59

S65	3	"20050155790"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/04/28 16:00
S66	6	("6774497").URPN.	USPAT	ADJ	ON	2009/10/16 15:42
S67	1	"6560122".PN.	USPAT; USOCR	ADJ	ON	2009/10/16 15:44
S68	1	"6365441".PN.	USPAT; USOCR	ADJ	ON	2009/10/16 16:07
S69	1	"6294840".PN.	USPAT; USOCR	ADJ	ON	2009/10/16 16:07
S70	1	"6271107".PN.	USPAT; USOCR	ADJ	ON	2009/10/16 16:07
S71	1	"6265776".PN.	USPAT; USOCR	ADJ	ON	2009/10/16 16:08
S72	1	"6228678".PN.	USPAT; USOCR	ADJ	ON	2009/10/16 16:08
S73	1	"6190940".PN.	USPAT; USOCR	ADJ	ON	2009/10/16 16:09
S74	1	"6121689".PN.	USPAT; USOCR	ADJ	ON	2009/10/16 16:29
S75	1	"5925936".PN.	USPAT; USOCR	ADJ	ON	2009/10/16 16:29
S76	34	("6190940").URPN.	USPAT	ADJ	ON	2009/10/16 16:30
S77	706994	(PCB or (printed circuit board) or PWB or (printed wiring board) or (circuit board) or (wiring board))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/10/16 16:53
S78	1165943	((IC or Chip or semiconductor) same (electrode or pad or terminal or contact))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/10/16 16:54
S79	2578456	(bump or ball or stud or post)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/10/16 16:55
S80	52864	S77 and S78 and S79	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/10/16 16:55
S81	542	(underfill or (underfill near2 resin)) same ((solder resist) or resist)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/10/16 16:56

S82	2512	(underfill or (underfill near2 resin)) and ((solder resist) or resist)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/10/16 16:56
S83	1470	S80 and S82	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/10/16 16:56
S84	493	volume and S83	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/10/16 16:56
S85	242	S84 and @ad<="20040329"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/10/16 17:00
S86	213	S81 and @ad<="20040329"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/10/16 17:36
S88	5718	(solder resist) same (aperture or hole or gap or void or open or opening)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/10/16 18:14
S89	1933	S80 and S88	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/10/16 18:14
S90	311	S82 and S89	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/10/16 18:15
S91	96	S90 and @ad<="20040329"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/10/16 18:15
S92	645	S83 and @ad<="20040329"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/10/16 18:29
S93	549	S92 not S91	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/10/16 18:29

S94	549	S93 not S90	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/10/16 18:29
S95	1	"10594844"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/10/17 14:26
S96	34	("6190940").URPN.	USPAT	ADJ	ON	2009/10/17 14:29
S97	0	("2002/0033525").URPN.	USPAT	ADJ	ON	2009/10/17 14:40
S98	2643	257/778.ccls.	USPAT	ADJ	ON	2009/10/17 14:45
S99	904	257/779.ccls.	USPAT	ADJ	ON	2009/10/17 14:45
S100	1404	257/780.ccls.	USPAT	ADJ	ON	2009/10/17 14:45
S101	4004	S98 or S99 or S100	USPAT	ADJ	ON	2009/10/17 14:45
S102	361	S101 and (solder resist)	USPAT	ADJ	ON	2009/10/17 14:48
S103	258	S102 and @ad<="20040329"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/10/17 14:49
S104	1031	(pitch or width) same (solder resist)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/10/17 14:50
S105	39	S104 and S101	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/10/17 14:50
S106	21	("6049122").URPN.	USPAT	ADJ	ON	2009/10/17 14:57
S107	1	"6049122".PN.	USPAT; USOCR	ADJ	ON	2009/10/17 15:01
S108	1	"5650595".PN.	USPAT; USOCR	ADJ	ON	2009/10/17 15:01
S109	1	"5397864".PN.	USPAT; USOCR	ADJ	ON	2009/10/17 15:01
S110	1	"5397864".PN.	USPAT; USOCR	ADJ	ON	2009/10/17 15:01
S111	1	"5218234".PN.	USPAT; USOCR	ADJ	ON	2009/10/17 15:01

S112	1	"4859808".PN.	USPAT; USOCR	ADJ	ON	2009/10/17 15:01
S113	1	"10644487"	USPAT	ADJ	ON	2009/10/17 15:12
S114	2	"10644487"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/10/17 15:12
S115	0	("2005/0155790").URPN.	USPAT	ADJ	ON	2009/10/17 15:12
S116	1	"6049122".PN.	USPAT; USOCR	ADJ	ON	2009/10/17 15:24
S117	21	("6049122").URPN.	USPAT	ADJ	ON	2009/10/17 15:24
S118	208	aperture volume	USPAT	ADJ	ON	2009/10/17 15:25
S119	0	S101 and S118	USPAT	ADJ	ON	2009/10/17 15:25
S120	23729	aperture same volume	USPAT	ADJ	ON	2009/10/17 15:25
S121	15	S101 and S120	USPAT	ADJ	ON	2009/10/17 15:26
S122	1	"6049122".PN.	USPAT; USOCR	ADJ	ON	2009/10/17 15:28
S123	2507	(solder (ball or bump)) same volume	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/10/17 15:43
S124	23729	aperture same volume	USPAT	ADJ	ON	2009/10/17 15:43
S125	71	S123 and S124	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/10/17 15:43
S126	46	S123 same S124	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/10/17 15:44
S127	59	("5658827").URPN.	USPAT	ADJ	ON	2009/10/17 15:47
S128	6517	(solder (ball or bump)) same (radius or diameter)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/10/17 16:01

S129	42	S124 and S128	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/10/17 16:01
S130	13213	(solder (ball or bump or globe)) same (radius or diameter or volume or width or height)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/10/17 16:05
S131	512788	(hole or aperture or opening or gap or void) same (volume or width or height)	USPAT	ADJ	ON	2009/10/17 16:06
S132	2521	S130 and S131	USPAT	ADJ	ON	2009/10/17 16:06
S133	1380	S130 same S131	USPAT	ADJ	ON	2009/10/17 16:06
S134	1091	S133 and @ad<="20040329"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/10/17 16:06
S135	125	S134 and (solder resist)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/10/17 16:07
S136	185	(hemisphere or hemispherical) near2 (solder bump)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/10/17 16:11
S137	3407	257/e21.511.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/10/17 16:29
S138	8	"6774497"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/10/19 11:00
S139	2	"6774497".pn.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2009/10/19 11:00

S140	18	("4661192" | "4818728" | "5341564" | "5611140" | "5768109" | "5808874" | "6051093" | "6074893" | "6130111" | "6190940" | "6202298" | "6329610" | "6375064" | "6410364" | "6531022" | "6720500" | "6774306").PN. OR ("7247508").URPN.	US-PGPUB; USPAT; USOCR	ADJ	ON	2010/10/25 10:53
S141	1	"7247508".pn.	US-PGPUB; USPAT; USOCR	ADJ	ON	2010/10/25 11:01
S142	33	("4617730" | "4954878" | "5010038" | "5086558" | "5218234" | "5426072" | "5447264" | "5468681" | "5504035" | "5817541" | "5821624" | "5866949" | "5915169" | "6020220" | "6242815").PN. OR ("6627998").URPN.	US-PGPUB; USPAT; USOCR	ADJ	ON	2010/10/25 15:03
S143	25	("5683942" | "5710071" | "5869886").PN. OR ("6049122").URPN.	US-PGPUB; USPAT; USOCR	ADJ	ON	2010/10/25 15:05
S144	3	("20040040742" | "6049122" | "7005585").PN. OR ("7474006").URPN.	US-PGPUB; USPAT; USOCR	ADJ	ON	2010/10/25 15:06
S145	909	(solder resist same (thick$4) same (underfill or resin or underfill ner2 resin))	US-PGPUB; USPAT; USOCR	ADJ	ON	2010/10/25 15:09
S146	909	(solder resist same (thick$4) same (underfill or resin or underfill near2 resin))	US-PGPUB; USPAT; USOCR	ADJ	ON	2010/10/25 15:09
S147	20	(solder resist same (thicker) same (underfill or resin or underfill near2 resin))	US-PGPUB; USPAT; USOCR	ADJ	ON	2010/10/25 15:09
S148	13	(solder resist same (thick$4) same (underfill near2 resin))	US-PGPUB; USPAT; USOCR	ADJ	ON	2010/10/25 15:10
S149	13	((solder near2 resist) same (thick$4) same (underfill near2 resin))	US-PGPUB; USPAT; USOCR	ADJ	ON	2010/10/25 15:14
S150	967	((solder near2 resist) same (thick$4) same (underfill or resin))	US-PGPUB; USPAT; USOCR	ADJ	ON	2010/10/25 15:14
S151	0	S150 and (soder resist same (overlap$3))	US-PGPUB; USPAT; USOCR	ADJ	ON	2010/10/25 15:15
S152	39	S150 and (solder resist same (overlap$3))	US-PGPUB; USPAT; USOCR	ADJ	ON	2010/10/25 15:15
S153	369	S146 and @ad<="20040329"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2010/10/25 15:20

S154	536	(solder resist with (thick$4) same (underfill or resin or underfill ner2 resin))	US-PGPUB; USPAT; USOCR	ADJ	ON	2010/10/25 15:28
S155	325	(solder resist with (thick$4) with (underfill or resin or underfill ner2 resin))	US-PGPUB; USPAT; USOCR	ADJ	ON	2010/10/25 15:28
S156	131	S155 and @ad<="20040329"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2010/10/25 15:28
S157	0	(solder resistt) with (thicker) with (underfill)	US-PGPUB; USPAT; USOCR	ADJ	ON	2010/10/26 10:35
S158	0	(solder resistt) with (thicker) with (underfill)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2010/10/26 10:35
S159	0	(solder resistt) with (thicker) with (resin)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2010/10/26 10:36
S160	0	(solder resist) with (thicker) with (underfill)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2010/10/26 10:36
S161	8	(solder resist) with (thicker) with (resin)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2010/10/26 10:36
S162	1149	(solder resist) same (height or thick$4) same (underfill or resin)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2010/10/26 10:38
S163	511	S162 and @ad<="20040329"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2010/10/26 10:39
S164	266	S163 and ((apertures or opening or hole) same (solder resist))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2010/10/26 10:40
S165	0	(thin near2 (underfill resin))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2010/10/26 10:56

S166	0	(thin near2 (under$1fill resin))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2010/10/26 10:56
S167	1637	(under$1fill resin)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2010/10/26 10:56
S168	15	S167 and (solder$1resist)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2010/10/26 10:56
S169	1	("2008/0149369").URPN.	USPAT	ADJ	ON	2010/10/26 12:16
S170	0	(11/944498).APP.	USPAT; USOCR	ADJ	ON	2010/10/26 12:17
S171	0	(11/944498).APP.	USPAT; USOCR	ADJ	ON	2010/10/26 12:17
S172	255	174/251.ccls.	USPAT; USOCR	ADJ	ON	2010/10/26 12:26
S173	471	S167 and (solder resist)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2010/10/26 13:04
S174	110	S173 and @ad<="20040329"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2010/10/26 13:05
S175	11	"6774497"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2010/10/26 13:17
S176	2	"6774497".pn.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2010/10/26 13:17
S177	2	"20040046252"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2010/10/26 13:20
S178	0	(solder resit) same (electrode or electrode pads) same (ovelap)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2010/10/26 13:45

S179	0	(solder resist) same (electrode or electrode pads) same (ovelap)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2010/10/26 13:45
S180	24	(solder resist) same (electrode or electrode pads) same (overlap)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2010/10/26 13:46
S181	1	"20040040742".PN.	US-PGPUB	ADJ	ON	2010/10/26 14:01
S182	1	"7005585".PN.	USPAT; USOCR	ADJ	ON	2010/10/26 14:01
S183	1	"6049122".PN.	USPAT; USOCR	ADJ	ON	2010/10/26 14:01
S184	3	("20040040742" | "6049122" | "7005585").PN. OR ("7474006").URPN.	US-PGPUB; USPAT; USOCR	ADJ	ON	2010/10/26 14:03
S185	25	("20010019178" | "20020036340" | "20020048916" | "20020074637" | "20020175421" | "20030047798" | "20030080437" | "20030116859" | "20030199123" | "20030211720" | "20030226254" | "20040087057" | "5391514" | "5611140" | "6163456" | "6165885" | "6175158" | "6190940" | "6322903" | "6399178" | "6498074" | "6498381" | "6661088" | "6903443").PN. OR ("7241675").URPN.	US-PGPUB; USPAT; USOCR	ADJ	ON	2010/10/26 14:05

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